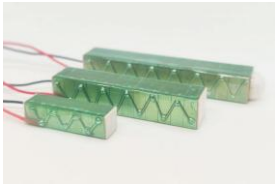
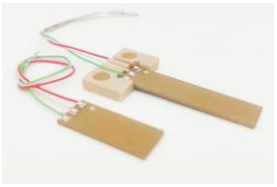
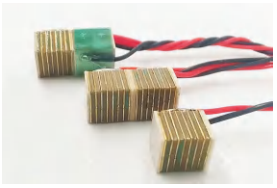
多层压电陶瓷

多层压电陶瓷是一种重要的换能材料，具有优良的机电耦合效应和对外场响应迅速且体积小、驱动电压低的特点，在机电换能及自动控制等领域得到了广泛应用。


多层压电陶瓷片


多层压电陶瓷叠堆


多层全陶瓷双晶片


多层压电陶瓷剪切片

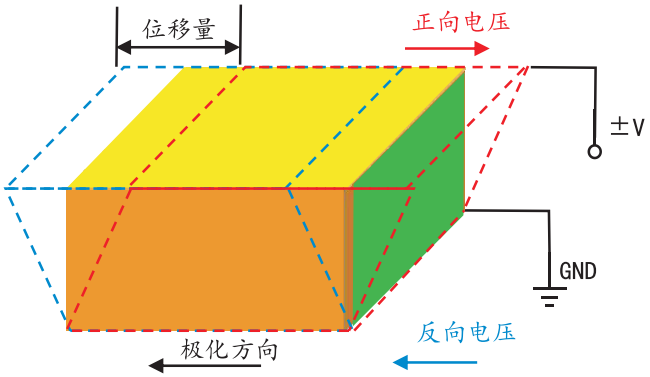
命名规则：

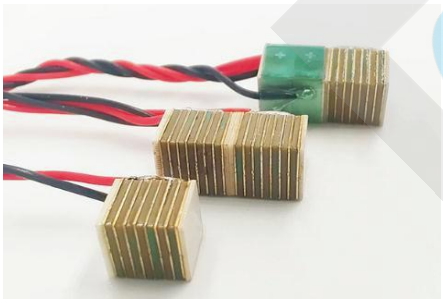
A	B	Bimoroph	压电双晶片	RD	Roung Chips	圆形压电片
	BH	Bimoroph With Holder	带基座压电双晶片	RG	Ring Chips	环形压电片
	C	Chips	方形压电片	S	Stack	方形压电叠堆
	CH	Chips With Hole	方形带中孔单片	SH	Stack With Hole	方形带中孔压电叠堆
	CS	Shear Chips	压电剪切片	SS	Shear Stack	压电剪切叠堆
	F	Stacks in Flexure	结构放大式压电叠堆	SRD	Round Stack	圆形压电叠堆
	SG	Stacks With Strain Gauges	带应变片压电叠堆	SRG	Ring Stack	环形压电叠堆
	CF	Co-Fired Piezoelectric	共烧压电陶瓷			
	B	Bimoroph	压电双晶片	RD	Roung Chips	圆形压电片
	BH	Bimoroph With Holder	带基座压电双晶片	RG	Ring Chips	环形压电片
	C	Chips	方形压电片	S	Stack	方形压电叠堆
	CH	Chips With Hole	方形带中孔单片	SH	Stack With Hole	方形带中孔压电叠堆
	CS	Shear Chips	压电剪切片	SS	Shear Stack	压电剪切叠堆
	F	Stacks in Flexure	结构放大式压电叠堆	SRD	Round Stack	圆形压电叠堆
	SG	Stacks With Strain Gauges	带应变片压电叠堆	SRG	Ring Stack	环形压电叠堆
	CF	Co-Fired Piezoelectric	共烧压电陶瓷			
B	驱动电压	1	-30 ~ 75V			
		2	-30 ~ 100V			
		3	-30 ~ 150V			
		4	-30 ~ 200V			
		5	-30 ~ 120V			
C	电极面尺寸	外径尺寸				
D	侧面尺寸	内径尺寸				
E	厚度尺寸					
F	端面处理	C1	一端氧化铝半球端帽	C3	氧化铝平面端帽	产品默认两端氧化铝平面
		C2	两端氧化铝半球端帽	C4	PZT不锈钢端帽	

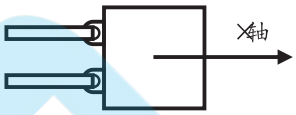
压电陶瓷剪切片

压电剪切片能提供横向的位移，将多个剪切片用环氧树脂和铜箔粘接成叠堆，能够提供更大的横向位移。

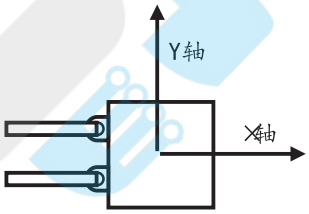
通过对剪切叠堆和Z轴运动的压电陶瓷进行叠加，可形成XY/XZ/YZ/XYZ等多轴移动的叠堆。



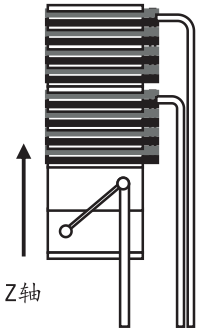




单轴位移方向



双轴位移方向



Z轴位移方向

压电剪切叠堆	电压	产品尺寸	电容（±15%）	频率	位移（±20% ）	最大推力
DCCS4-050505	±200V	5.0×5.0×0.5 mm	1.7 nF ± 15%	1800 kHz	± 1.3 um ± 20%	50 N
DCCS4-050518	±200V	5.0×5.0×1.8 mm	1.7 nF ± 15%	1900 kHz	± 1.3 um ± 20%	50 N
DCSS4-050506	±200V	5.0×5.0×6.0 mm	X:10 nF ± 15%	2100 kHz	± 7.0 um ± 15%	50 N
DCSS4-050512	±200V	5.0×5.0×12.0 mm	X/Y:10 nF ± 15%	2100 kHz	± 7.0 um ± 15%	50 N
DCSS4-050518	±200V 0～150V	5.0×5.0×18.0 mm	X/Y:10 nF ± 15% Z:530nF ± 15%	2100 kHz 125 kHz	± 7.0 um ± 15% ± 7.0 um ± 15%	50 N 1000 N